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To the Honorable Commissioner of Patents and Trademarks:	: Please record the attached original documents or copy thereof.	_1						
Name of conveying party(ies):		960						
Dong-hun LEE	Name: Samsung Electronics Co., Ltd.							
Additional name(s) of conveying party(ies) attached? 📮 Yes 🛂 No		_						
3. Nature of conveyance:	7							
🗘 Assignment 📮 Merger	Street Address: 416, Maetan-dong, Yeongtong-gu							
Security Agreement								
Other	Suwon-si, Gyeonggi-do City:State:_KOREA_Zip:	- -						
Execution Date: June 16, 2006	Additional name(s) & address(es) attached? 📮 Yes 🗀 No							
Application number(s) or patent number(s):								
If this document is being filed together with a new appl	lication, the execution date of the application is: 6/19/2006	_						
A. Patent Application No.(s)	B. Patent No.(s)							
Additional numbers at	ttached? Yes V No							
5. Name and address of party to whom correspondence	6. Total number of applications and patents involved:							
concerning document should be mailed: Name: John E. Holmes	7. Total fee (37 CFR 3.41)\$_40.00							
Internal Address:	✓j Enclosed							
Roylance, Abrams, Berdo & Goodman, LLP	Authorized to be charged to deposit account							
Street Address: 1300 19th Street, N.W., Suite 600	8. Deposit account number:							
	18-2220	_						
City: Washington State: DC Zip: 20036	(Attach duplicate copy of this page if paying by deposit account)							
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 Statement and signature. To the best of my knowledge and belief, the foregoing is a true copy of the original document. Marcus R. Mickney 	information is true and correct and any attached copy June 19, 2006	_						
To the best of my knowledge and belief, the foregoing is a true copy of the original document.	D.1.	_						

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Washington, D.C. 20231

<u>ASSIGNMENT</u>

WHEREAS, I, Dong-hun LEE, a citizen of the Republic of Korea, residing at 301 Hanyang Heights Villa, 245-16 Seongsan 1-dong, Mapo-gu, Seoul, Republic of Korea (hereinafter "ASSIGNOR"), have made a certain invention entitled "LIGHT SCANNING UNIT AND IMAGE FORMING APPARATUS HAVING THE SAME" for which I am making application for Letters Patent of the United States, which application is being executed concurrently herewith; and

WHEREAS, Samsung Electronics Co., Ltd., a corporation duly organized under the laws of the Republic of Korea, located and doing business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (hereinafter "ASSIGNEE"), is desirous of acquiring the entire right, title and interest in and to the aforementioned invention and the aforementioned application and any and all United States Letters Patent to be obtained on said invention and/or application;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN that for good and valuable consideration paid to me by said ASSIGNEE, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, by these presents do hereby sell, assign, set over and transfer unto the said ASSIGNEE, its successors, legal representatives or assigns, the entire right, title and interest in and to the aforesaid invention in and for the United States; and in, to and under the aforesaid United States application and any divisional, continuing, substitute or reissue applications or supplementary disclosures which may be filed on said invention in the United States; and our right to file said applications and claim priority under the provisions of any international treaty or convention; and in and to any Letters Patent of the United States issued or granted on said invention and/or said applications;

AND I HEREBY authorize and request the U.S. Patent and Trademark Office or other issuing authority to issue any and all patents on said invention and/or said applications to said ASSIGNEE as sole assignee;

AND I HEREBY covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any assignment or other instrument in conflict herewith;

AND I HEREBY further covenant and agree to communicate to said ASSIGNEE, or its legal representatives, successors or assigns, any facts relating to said invention, including evidence for interference purposes or other proceedings, whenever requested, and to testify in any interference or in any other legal proceeding, when requested, and to execute and deliver on request all lawful papers required to make any of the foregoing provisions effective; and to perform the aforesaid communicating, executing and delivering, without any payment except expenses and to perform the aforesaid testifying for reasonable compensation; and generally to do everything possible to aid the said ASSIGNEE, its successors, legal representatives or assigns to obtain and enforce proper patent protection on and for said

ASSIGNMENT

PATENT REEL: 017989 FRAME: 0729 invention in the United States, and likewise I make these provisions binding upon our heirs, legal representatives and/or administrators.

I hereby grant the firm of Roylance, Abrams, Berdo & Goodman, L.L.P. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

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Witness

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ASSIGNMENT

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